

Amendments to the Specification:

Please replace the paragraph beginning at page 7, line 6 of the English translation of the specification with the following amended paragraph:

-- The third exemplary embodiment, illustrated in Fig. 3, is a miniature light-emitting diode comprising a flexible leadframe 10, an LED chip 1 with an active, radiation-emitting region, and a molded plastic part 5. Said flexible leadframe 10 is made of 60  $\mu\text{m}$  thick metal foil 101 and 60  $\mu\text{m}$  thick plastic film ~~12~~ 102, which are glued together very precisely. The plastic film can be made of silicone plastic. --

Please replace the paragraph beginning at page 7, line 15 of the English translation of the specification with the following amended paragraph:

-- To be able to produce as many components as possible on the flexible frame, the encapsulation is done for example by “cavity-to-cavity molding,” as shown in Fig. 4, in which a molded plastic part 5 that encapsulates the LED chip 1 and the bonding wire 2 is fabricated over each flexible leadframe 10. The number of injection channels is reduced by running an injection channel ~~55~~ through cavities 50 of the components. The molded plastic part is made of the same material as the molded plastic part of the aforesaid exemplary embodiments. --

Please add the following new paragraph after the paragraph ending at page 4, line 24 of the English translation of the specification:

-- Fig. 4 is a schematic diagram showing an injection channel running between multiple exemplary components. --